

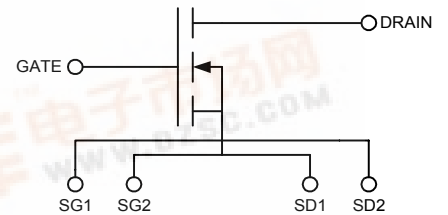
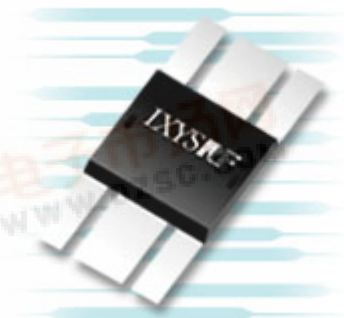


IXZ308N120
Z-MOS RF Power MOSFET

N-Channel Enhancement Mode Switch Mode RF MOSFET
Low Capacitance Z-MOS™ MOSFET Process
Optimized for RF Operation
Ideal for Class C, D, & E Applications

V_{DSS} = 1200 V
I_{D25} = 8.0 A
R_{DS(on)} = 2.1 Ω
P_{DC} = 880 W

Symbol	Test Conditions	Maximum Ratings
V _{DSS}	T _J = 25°C to 150°C	1200 V
V _{DGR}	T _J = 25°C to 150°C; R _{GS} = 1 MΩ	1200 V
V _{GS}	Continuous	±20 V
V _{GSM}	Transient	±30 V
I _{D25}	T _c = 25°C	8 A
I _{DM}	T _c = 25°C, pulse width limited by T _{JM}	40 A
I _{AR}	T _c = 25°C	8 A
E _{AR}	T _c = 25°C	TBD mJ
dv/dt	I _S ≤ I _{DM} , di/dt ≤ 100A/μs, V _{DD} ≤ V _{DSS} , T _J ≤ 150°C, R _G = 0.2Ω	5 V/ns
	I _S = 0	>200 V/ns
P _{DC}		880 W
P _{DHS}	T _c = 25°C, Derate 4.4W/°C above 25°C	440 W
P _{DAMB}	T _c = 25°C	3.0 W
R _{thJC}		0.17 C/W
R _{thJHS}		0.34 C/W



Features

- Isolated Substrate
 - high isolation voltage (>2500V)
 - excellent thermal transfer
 - Increased temperature and power cycling capability
- IXYS advanced Z-MOS process
- Low gate charge and capacitances
 - easier to drive
 - faster switching
- Low R_{DS(on)}
- Very low insertion inductance (<2nH)
- No beryllium oxide (BeO) or other hazardous materials

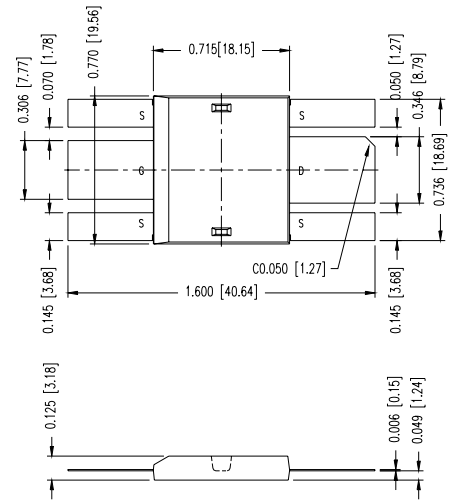
Advantages

- Optimized for RF and high speed
- Easy to mount—no insulators needed
- High power density

		min.	typ.	max.	
V _{DSS}	V _{GS} = 0 V, I _D = 4 ma	1200			V
V _{GS(th)}	V _{DS} = V _{GS} , I _D = 250μA	3.5		6.5	V
I _{GSS}	V _{GS} = ±20 V _{DC} , V _{DS} = 0			±100	nA
I _{DSS}	V _{DS} = 0.8V _{DSS} V _{GS} =0			50 1	μA mA
R _{DS(on)}	V _{GS} = 20 V, I _D = 0.5I _{D25} Pulse test, t ≤ 300μS, duty cycle d ≤ 2%		2.1		Ω
g _{fs}	V _{DS} = 50 V, I _D = 0.5I _{D25} , pulse test		10.1		S
T _J		-55		+175	°C
T _{JM}			175		°C
T _{stg}		-55		+ 175	°C
Weight	1.6mm(0.063 in) from case for 10 s		300		°C
			3.5		g



Symbol	Test Conditions	Characteristic Values		
		(T _J = 25°C unless otherwise specified)		
		min.	typ.	max.
R _G				1 Ω
C _{iss}			1960	pF
C _{oss}	V _{GS} = 0 V, V _{DS} = 0.8 V _{DSS(max)} , f = 1 MHz		59	pF
C _{rss}			9.2	pF
C _{stray}	Back Metal to any Pin		33	pF
T _{d(on)}			4	ns
T _{on}	V _{GS} = 15 V, V _{DS} = 0.8 V _{DSS} I _D = 0.5 I _{DM}		5	ns
T _{d(off)}	R _G = 1 Ω (External)		4	ns
T _{off}			6	ns



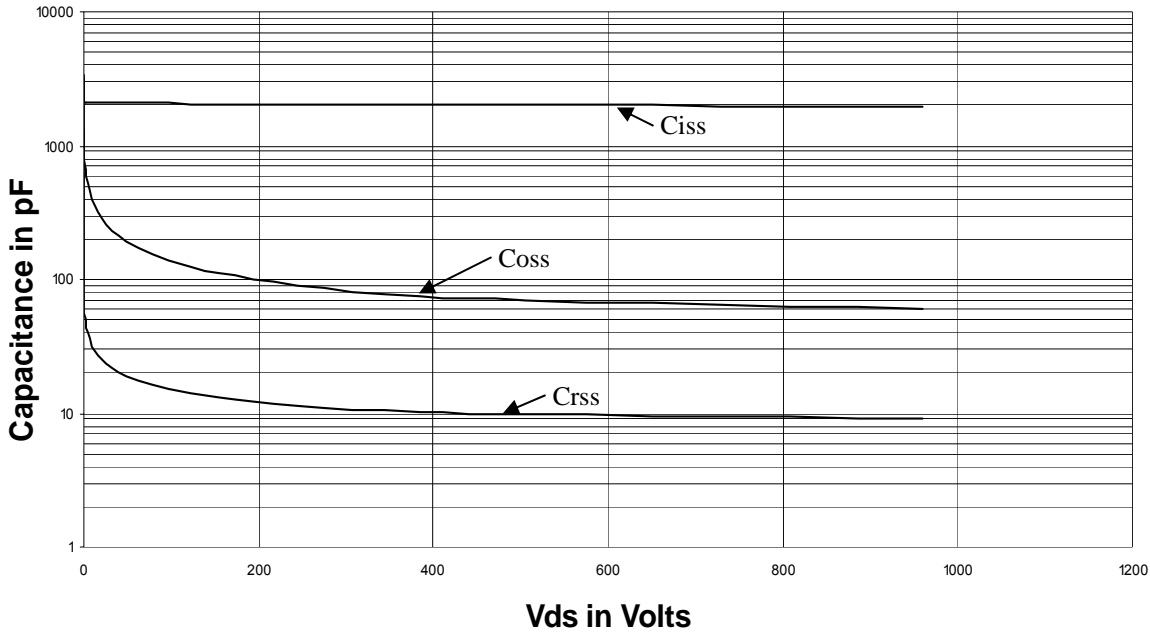
Source-Drain Diode		Characteristic Values		
		(T _J = 25°C unless otherwise specified)		
Symbol	Test Conditions	min.	typ.	max.
I _S	V _{GS} = 0 V			8 A
I _{SM}	Repetitive; pulse width limited by T _{JM}			48 A
V _{SD}	I _F =I _S , V _{GS} =0 V, Pulse test, t ≤ 300μs, duty cycle ≤2%			1.5 V
T _{rr}			TBD	ns

For detailed device mounting and installation instructions, see the “DE-Series MOSFET Mounting Instructions” technical note on IXYS RF’s web site at www.ixysrf.com/Technical_Support/App_notes.html

IXYS RF reserves the right to change limits, test conditions and dimensions.

IXYS RF MOSFETS are covered by one or more of the following U.S. patents:

- | | | | | | |
|-----------|-----------|-----------|-----------|-----------|-----------|
| 4,835,592 | 4,860,072 | 4,881,106 | 4,891,686 | 4,931,844 | 5,017,508 |
| 5,034,796 | 5,049,961 | 5,063,307 | 5,187,117 | 5,237,481 | 5,486,715 |
| 5,381,025 | 5,640,045 | 6,404,065 | 6,583,505 | 6,710,463 | 6,727,585 |
| 6,731,002 | | | | | |



IXZ308N120 Capacitances verses Vds

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